Claims

1. A flat carrier provided with holders for separated electronic components, suitable for use in a method for visual inspection of separated electronic components, comprising:

- a flat metal platform provided with a space recessed into the flat metal platform, which recessed space is opened to one of the flat sides of the flat metal platform, and
- a plastic carrier structure arranged form-fittingly in the recessed space, wherein:
- the holders for the separated electronic components are formed from the carrier structure made of plastic;
- the form-fitting arrangement is such that a contact side of the plastic carrier structure and an edge of the metal platform connecting thereto connect to each other in one surface;
- the holders for the separated electronic components are formed by receiving spaces recessed into the plastic;
- the receiving spaces recessed into the plastic are provided with chamfered positioning edges; and
- further, the plastic of the carrier structure is mixed with a conductor.

2. The flat carrier as claimed in claim 1, wherein the space recessed into the flat metal platform is opened to only one of the flat sides of the flat metal platform.

3. The flat carrier as claimed in claim 1, wherein the holders for the separated electronic components are formed by protruding plastic carrying elements.

4. The flat carrier as claimed in claim 1, wherein the plastic of the carrier structure is introduced as moulding resin into the recessed space in the flat metal platform.

5. The flat carrier as claimed in claim 1, wherein the flat metal platform is manufactured from aluminium.

6. The flat carrier as claimed in claim 1, wherein the plastic has an increased surface roughness in that the surface is abraded.

7. The flat carrier as claimed in claim 1, wherein the holders for the separated electronic components which are formed by the plastic of the carrier structure are provided with suction openings which are connected to at least one central suction line.

8. A method for visual inspection of separated electronic components, comprising the processing steps of:

A) loading a number of separated electronic components into a flat carrier as claimed in claims 1-7;

B) relatively displacing the carrier loaded with separated electronic components relative to a camera; and

C) visually inspecting the separated electronic components held by the carrier using the camera.

9. The method as claimed in claim 8, wherein the separated electronic components are brought with a minimum accuracy into a secured position during processing step A) using positioning edges arranged in the plastic carrier structure.

10. The method as claimed in claim 8, wherein an electrostatic charge present in the plastic carrier structure is at least partially discharged by means of an ionized gas flow.

11. The method as claimed in claim 8, wherein the mutual positions of the separated electronic components and the holders for the separated electronic components are secured by means of underpressure.